

## **Application Data Sheet**

### **Application Information**

Application Type:: Regular  
Subject Matter:: Utility  
Title:: Die Bonding Apparatus With Automatic  
Die And Lead Frame Image Matching System  
Attorney Docket Numer:: IDT-1661  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Suggested Drawing Figure:: 4  
Total Drawing Sheets:: 3  
Small Entity:: No  
Petition included?:: No  
Secrecy Order in Parent Appl.?:: No

### **Inventor Information**

Inventor Authority type:: Inventor  
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### **Representative Information**

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**Foreign Priority Information**

Country:: Application Number:: Filing Date::  
Malaysia PI 20012544 05/29/01

**Assignee Information**

Assignee Name:: Integrated Device Technology, Inc.

O-988888-E-000000000000